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Third State of Art Lead-free Technology Workshop

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PAPER TITLE	AUTHOR(S)	VIEW PRESENTATION
Advances in Sn-Ag-Cu and Sn-Ag-Cu-X Alloy Development for Pb-free Electronic Solder Applications	*Iver E. Anderson, Joel Harringa, Jason Walleser and David Rehbein, Iowa State University*	Launch Presentation
Interfacial Evolution between Solder and Metallization	*Kwang-Lung Lin, National Cheng-Kung University*	Launch Presentation
Alternate Pb Free Solder Alloys for High Strain Rate Mechanical Loading Conditions	*Ahmer Syed, Amkor Technology*	Launch Presentation
Conductive Anodic Filament Formation	*Laura J.Turbini, University of Toronto*	Launch Presentation
Nano-Enabled Low Temperature Lead-free Solders for Advanced Electronic Packaging	*Alan Rae, Gregory Berube and Suv Sengupta, NanoDynamics, Inc.,*	Launch Presentation
Challenges of Densification in Electronics Packages and Assembly	*Fay Hua, Intel Corporation*	Launch Presentation